Package Outline Drawing

W4x5.20G
20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm PITCH)
Rev 0, 11/13

NOTES:
2. Dimension is measured at the maximum bump diameter parallel to primary datum [Z].
3. Primary datum [Z] and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.

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Plastic Packages for Integrated Circuits